

Amendments to the Specification

Please replace the paragraph at page 7, line 15 to page 8, line 7 with the following amended paragraph:

A preferable optical bond-wire interconnection for electrical signals is schematically illustrated on FIG. 1. Optical bond-wires 3 may be used to interconnect monolithic microwave integrated circuits (MMIC) 2, for example. The MMICs can be located on the same ~~microchip~~ multichip module (MCM) 1 or on different MCMs. As can be seen from FIG. 1, the length of optical bond-wires 3 can be substantially longer than that of electric wires 4. There is no need for MMICs to be immediately adjacent in the case of optical bond-wire interconnections. As pointed out above, the length of optical bond-wires can reach hundreds of meters.